

Halfgeleiderelementen - Omhulsels,  
afmetingen en overige dimensionele  
aspecten - Deel 6-3: Wijze van tekenen  
van omhulsels van halfgeleiderelementen  
voor oppervlaktemontage -  
Meetmethoden voor de bepaling van de  
afmetingen van quad flat packs (QFP)  
(IEC 60191-6-3:2000, IDT)

Mechanical standardization of semiconductor devices - Part 6-3:  
General rules for the preparation of outline drawings of surface mounted  
semiconductor device packages - Measuring methods for package  
dimensions of quad flat packs (QFP) (IEC 60191-6-3:2000, IDT)

februari 2001  
ICS 31.080

Als Nederlandse norm is aanvaard:

- EN 60191-6-3:2000, IDT
- IEC 60191-6-3:2000, IDT

Nederlands Elektrotechnisch Comité (NEC)  
Normcommissie NEC 47 "Halfgeleiders"

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<u>vermelde norm</u>	<u>Nederlandse norm</u>	<u>titel</u>
IEC 60191-6:1990	NEN-IEC 60191-6:2000	Halfgeleiderelementen - Omhulsels, afmetingen en overige dimensionele aspecten - Deel 6: Wijze van tekenen van omhulsels van halfgeleiderelementen voor oppervlaktemontage (en,fr)

Voorbeeld  
Preview

English version

**Mechanical standardization of semiconductor devices**  
**Part 6-3: General rules for the preparation of outline drawings**  
**of surface mounted semiconductor device packages -**  
**Measuring methods for package dimensions of quad flat packs (QFP)**  
(IEC 60191-6-3:2000)

Normalisation mécanique des dispositifs  
à semiconducteurs  
Partie 6-3 : Règles générales pour  
la préparation des dessins  
d'encombrement des dispositifs à  
semiconducteurs à montage en surface -  
Méthodes de mesure pour les boîtiers  
plats quadrangulaires (QFP)  
(CEI 60191-6-3:2000)

Mechanische Normung von  
Halbleiterbauelemente  
Teil 6-3: Allgemeine Regeln für die  
Erstellung von Gehäusezeichnungen  
von SMD-Halbleitegehäusen -  
Meßverfahren für QFP-Gehäusemaße  
(IEC 60191-6-3:2000)

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European Committee for Electrotechnical Standardization  
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Europäisches Komitee für Elektrotechnische Normung

Central Secretariat: rue de Stassart 35, B - 1050 Brussels

## Foreword

The text of document 47D/370/FDIS, future edition 1 of IEC 60191-6-3, prepared by SC 47D, Mechanical standardization of semiconductor devices, of IEC TC 47, Semiconductor devices, was submitted to the IEC-CENELEC parallel vote and was approved by CENELEC as EN 60191-6-3 on 2000-11-01.

The following dates were fixed:

- latest date by which the EN has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2001-08-01
- latest date by which the national standards conflicting with the EN have to be withdrawn (dow) 2003-11-01

Annexes designated "normative" are part of the body of the standard.  
In this standard, annex ZA is normative.  
Annex ZA has been added by CENELEC.

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## Endorsement notice

The text of the International Standard IEC 60191-6-3:2000 was approved by CENELEC as a European Standard without any modification.

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**Annex ZA**  
(normative)

**Normative references to international publications  
with their corresponding European publications**

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NOTE When an international publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60191-6	1990	Mechanical standardization of semiconductor devices Part 6: General rules for the preparation of outline drawings of surface mounted semiconductor device packages	-	-

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Voorbeelden  
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# INTERNATIONAL STANDARD

**IEC**  
**60191-6-3**

First edition  
2000-09

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## **Mechanical standardization of semiconductor devices –**

### **Part 6-3: General rules for the preparation of outline drawings of surface mounted semiconductor device packages – Measuring methods for package dimensions of quad flat packs (QFP)**

*Normalisation mécanique des dispositifs à semiconducteurs –*

*Partie 6-3:  
Règles générales pour la préparation des dessins  
d'encombrement des dispositifs à semiconducteurs  
à montage en surface – Méthodes de mesure pour  
les boîtiers plats quadrangulaires (QFP)*



Reference number  
IEC 60191-6-3:2000(E)

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